



4200W Rated Capacity BGA Rework Station with 100% Duty Cycle and 97*70*83CM Specification for Automatic BGA Repair

Basic Information

- Place of Origin: China
- Brand Name: Wisdomshow BGA
- Minimum Order Quantity: 1
- Price: 18800



Product Specification

- Model NO.: WDS-850
- Rated Capacity: 4200W
- Rated Duty Cycle: 100%
- Machine Type: BGA Repair Machine
- Weight: 210 Kg
- Dimensions: 97*70*83CM
- Production Capacity: 5000
- Up-heater Power: 1200W
- Down-heater Power: 1200W
- IR Power: 5000W
- Max Plate Size: 650*610mm
- Preheating Area: 500*420mm
- Heat Resistance: 1800 C
- Pressure Control: 10 Grams
- Temperature Control: 8 Segments



More Images



Product Description

BGA Rework Station - Automatic Chip Removal and Mounting Machine

Product Overview

Our BGA Rework Station is designed for professional chip replacement and repair in laptops, mobile phones, gaming consoles (Xbox 360, PS3/PS4), and other electronic devices. Ideal for repair shops and factories providing after-sales service and component rework.

Repair Process

- Desoldering: Separate BGA chip from motherboard
- Pad cleaning
- Reballing or direct BGA chip replacement
- Precision alignment (using silk frame or optical camera)
- Soldering: Install new BGA chip

Applications

- Watch/Mobile/Cell phone repair
- Notebook/Laptop/Computer repair
- XBOX 360/PS2/PS3/PS4/Wii game console repair
- SMD/SMT/IC BGA rework including iCloud removal
- BGA VGA, CPU, GPU, ECU and car motherboard soldering/desoldering
- BGA chips, QFP QFN chip, PC, PLCC PSP PSY rework

Key Features

- Integrated hot air head and mounting head with automatic soldering/desoldering
- Independent 3-zone heating system with synchronized upper/lower heater movement
- High-precision PCB slider for accurate BGA mounting
- German-imported preheating table (500×420mm) with heat-resistant glass (up to 1800°C)
- Motor-controlled X/Y axis movement for precise alignment
- Maximum PCB size capacity: 650×610mm with no repair dead corners
- Built-in vacuum pump with 360° rotation and fine-adjustable suction nozzle
- Automatic BGA height detection with pressure control (down to 10g)

Technical Specifications

Heating System	Independent 3-zone temperature control
Upper Heater Power	1200W
Lower Heater Power	1200W
IR Power	5000W

Optical Alignment System

High-definition CCD color optical alignment system with HD LCD monitor

Operation System

HD touch interface with 8-segment temperature control and real-time curve analysis

Safety Features

- Password protection against unauthorized modifications
- Dual over-temperature protection



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